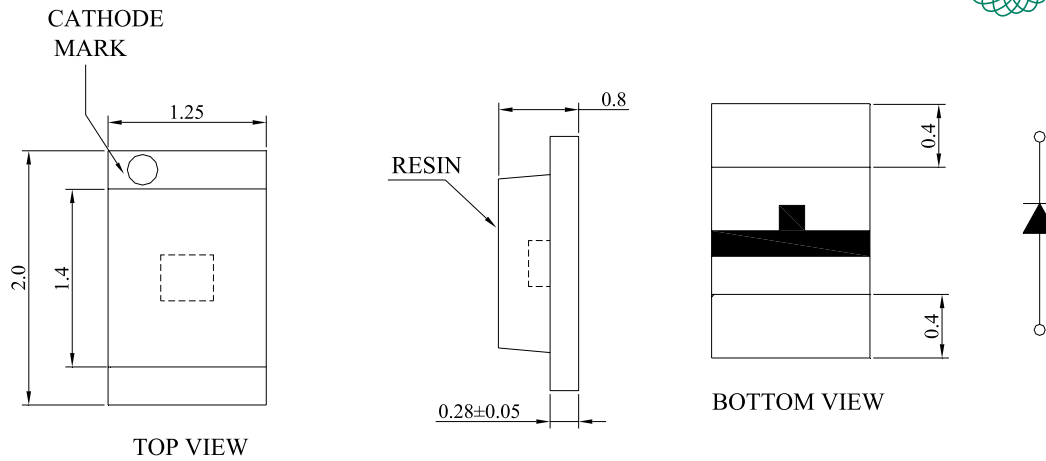


SMD Chip LED



Package Dimensions:



All dimensions are in mm
Tolerance: ± 0.1 mm

Absolute Maximum Ratings at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power Dissipation	P_D	66	$^\circ\text{C}$
Reverse Voltage	V_R	4	V
D.C. Forward Current	I_f	30	mA
Pulsed Forward Current (1 / 10 Duty Cycle, 0.1ms Pulse Width)	I_f (Peak)	80	mA
Operating Temperature Range	$T_{opr.}$	-40 to +80	$^\circ\text{C}$
Storage Temperature Range	$T_{stg.}$	-40 to +85	$^\circ\text{C}$
Soldering Temperature	$T_{sld.}$	Reflow Soldering: 260°C for 10sec.	

Electrical & Optical Characteristics: Hyper Red

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I_v	$I_f = 20\text{mA}$	-	15	-	mcd
Forward Voltage	V_f	$I_f = 20\text{mA}$	1.6	-	2.2	V
Peak Wavelength	λ_p	$I_f = 20\text{mA}$	-	660	-	nm
Dominant Wavelength	λ_d	$I_f = 20\text{mA}$	-	643	-	nm
Reverse Current	I_r	$V_r = 5\text{V}$	-	-	100	μA
Viewing Angle	$2\theta_{1/2}$	$I_f = 20\text{mA}$	-	140	-	deg
Spectrum Line Halfwidth	$\Delta\lambda$	$I_f = 20\text{mA}$	-	20	-	nm

Note: 1. The data is tested by an IS tester
2. Customer's special requirements are also welcome.



SMD Chip LED

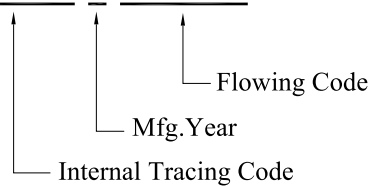


Product Specification

	Specification	Material	Quantity
Iv	M: 7,56 – 11.0 mcd N: 11.0 – 16.5 mcd P: 16.5 – 24.4 mcd @ 20mA	-	-
λd	636 – 650 nm @ 20mA	-	-
Vf	F: 1.6 – 1.8 V G: 1.8 – 2.0 V H: 2.0 – 2.2 V @ 20mA	-	-
Ir	< 100μA @ Vr=5V	-	-
Resin	White diffused	Epoxy resin	-
Carrier tape	-	Conductive black tape	4,000pcs per reel
Reel	-	White	-
Label	LT standard	Paper	-
Packing Bag	250mm × 220mm	Aluminium laminated bag	One reel one bag
Carton	LT standard	Paper	Non-specified
Others:		-	

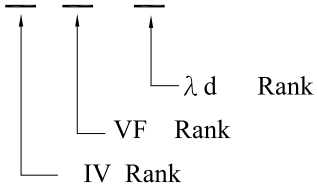
Lot No.:

W O Z A 3 0 0 0 6 2



BIN CODE :

X X - X

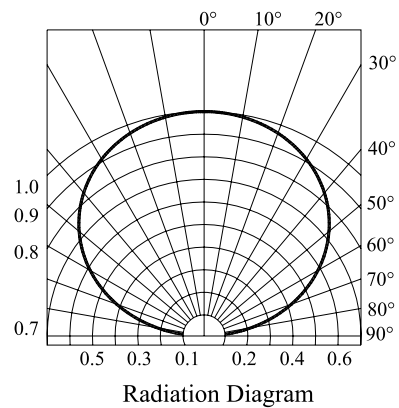
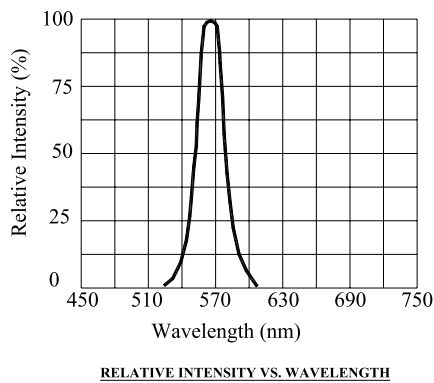
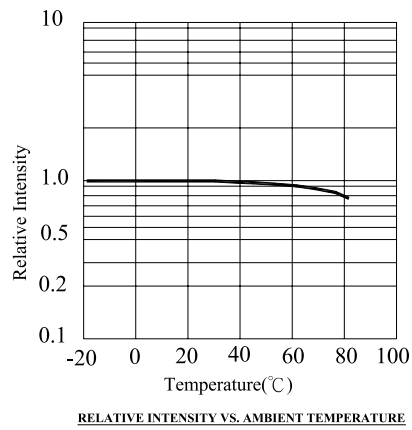
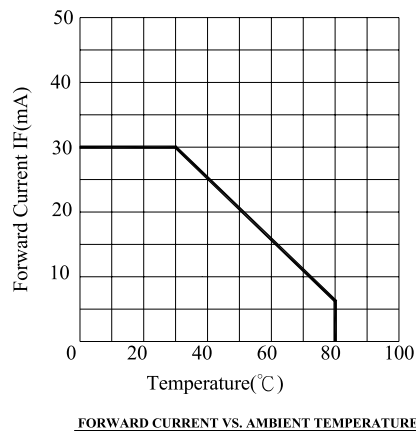
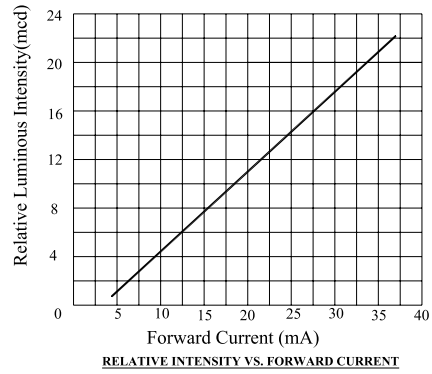
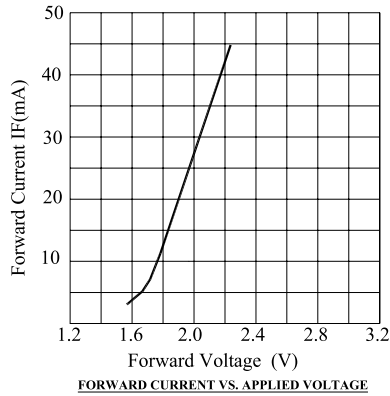


SMD Chip LED



Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)



Recommended Storage Environment:

- Temperature: 5°C to 30°C (41°F to 86°F)
- Humidity: 60% RH Max.
- Use within 7 days after opening of sealed vapour/ESD barrier bags

If moisture absorbent material (silica gel) has faded away or LEDs have exceeded the storage time, baking treatment should be performed using the following conditions:

- Baking Treatment : 60 ± 5°C for 24 hours
- Fold the opened bag firmly and keep in dry environment

Reflow Soldering

Recommended use of upper and lower heater type reflow furnace.

- 260°C max for up to 10 seconds, one time only
- Pre-heat is 150°C max for up to 2 minutes max
- In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm

Cleaning

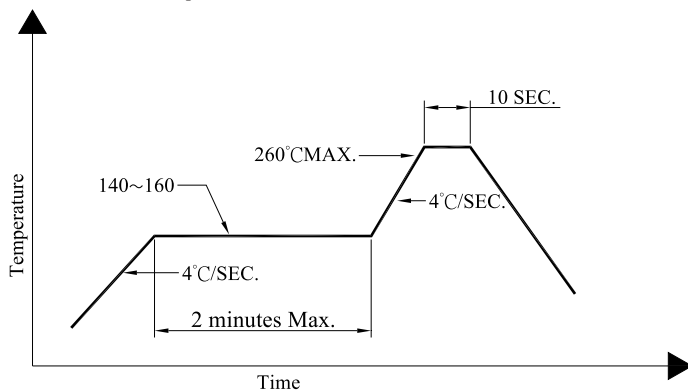
Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

- Avoid using organic solvent
- Recommend ultrasonic method 300W max.

Packaging

- EIA-481A standard package
- In 8mm tape on 4,000pcs diameter reels sealed in vapour/ESD barrier bags

Reflow Temp / Time:



Part Number Table

LED Chip		Lens Colour	Part Number
Material	Emitting Colour		
AlGaAs / GaAs	Red	White diffused	703-0107

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